

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.43295	100.0	1
Subtotal				0.43295	100	1
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.59311	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
Subtotal				1.59327	100	3.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.012	0.03	0.02772
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.09239
	Copper alloy	Copper (Cu)	7440-50-8	39.84052	99.6	92.02044
	Pure metal layer	Silver (Ag)	7440-22-4	0.108	0.27	0.24945
Subtotal				40.00052	100	92.39
Adhesive	Polymer	Paraffin wax	8002-74-2	0.1853	20.0	0.428
	Polymer	Epoxy resin system		0.07412	8.0	0.1712
	Filler	Silver (Ag)	7440-22-4	0.66709	72.0	1.5408
Subtotal				0.92651	100	2.14
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.42571	2.5	3.293
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.27714	7.5	9.879
	Filler	Silica -amorphous-	7631-86-9	21.10057	37.0	48.7364
	Pigment	Carbon black	1333-86-4	0.28514	0.5	0.6586
	Polymer	Epoxy resin system		8.55428	15.0	19.758
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.10057	37.0	48.7364
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28514	0.5	0.6586
Subtotal				57.02855	100	131.72
Wire	Copper alloy	Copper (Cu)	7440-50-8	0.01818	100.0	0.042
Subtotal				0.01818	100	0.042
Total				99.99998	100	230.972

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